



IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Quat T. Vu et al.

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON
AN INTERFACIAL LAYER THEREOF

Docket No.: 884.384US1

Filed: April 30, 2001

Examiner: Asok K Sarkar

Customer No.: 21186

Serial No.: 09/845,881

Due Date: November 2, 2004

Group Art Unit: 2829

Confirmation No.: 4041

Commissioner for Patents

Attn: MAIL STOP ISSUE FEE

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SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number: 21186

By

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Chris Hammond

Name

Chris Hammond

Signature



S/O 09/845,881

PATENT

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant:	Quat T. Vu et al.	Examiner:	Asok K. Sarkar
Serial No.:	09/845,881	Group Art Unit:	2827
Filed:	April 30, 2001	Docket:	884.384US1
Title:	MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF		
Assignee:	Intel Corporation	Customer No.:	21186

COMMUNICATION CONCERNING RELATED APPLICATION(S)

Mail Stop Issue Fee
Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related application(s) in the above-identified patent application:

<u>Serial/Patent No.</u>	<u>Filing Date</u>	<u>Attorney Docket</u>	<u>Title</u>
09/946749	September 5, 2001	Intel P10664	LOW COST MICROELECTRONIC CIRCUIT PACKAGE
09/845896	April 30, 2001	Intel P10665	HIGH PERFORMANCE, LOW COST MICROELECTRONIC CIRCUIT PACKAGE WITH INTERPOSER
09/854539	May 14, 2001	884.415US1	POLYMERIC ENCAPSULATION MATERIAL WITH FIBROUS FILLER FOR USE IN MICROELECTRONIC CIRCUIT PACKAGING
09/903025 6586276	July 11, 2001	884.418US1	METHOD FOR FABRICATING A MICROELECTRONIC DEVICE USING WAFER-LEVEL ADHESION LAYER DEPOSITION
09/861689	May 21, 2001	884.426US1	METHOD FOR PACKAGING A MICROELECTRONIC DEVICE USING ON-DIE BOND PAD EXPANSION

COMMUNICATION CONCERNING RELATED APPLICATIONS

Serial Number: 09/845,881

Filing Date: April 30, 2001

Title: MICROELECTRONIC DEVICE HAVING SIGNAL DISTRIBUTION FUNCTIONALITY ON AN INTERFACIAL LAYER THEREOF

Assignee: Intel Corporation

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Respectfully submitted,

QUAT T. VU ET AL.

By Applicants' Representatives,

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